

Description

The TD814 series combine two AlGaAs infrared emitting diodes as the AC input which is optically coupled to a silicon planar phototransistor detector in a plastic DIP4 package with different lead forming options.

With the robust coplanar double mold structure, TD814 series provide the most stable isolation feature.

Features

- High isolation 5000 VRMS
- CTR flexibility available see order information
- AC input with transistor output
- Operating temperature range 55 °C to
 110 °C
- REACH compliance
- Halogen free(optional)
- MSL class 1
- Regulatory Approvals
 - UL UL1577
 - VDE EN60747-5-5(VDE0884-5)
 - CQC GB4943.1, GB8898
 - cUL- CSA Component Acceptance
 Service Notice No. 5A

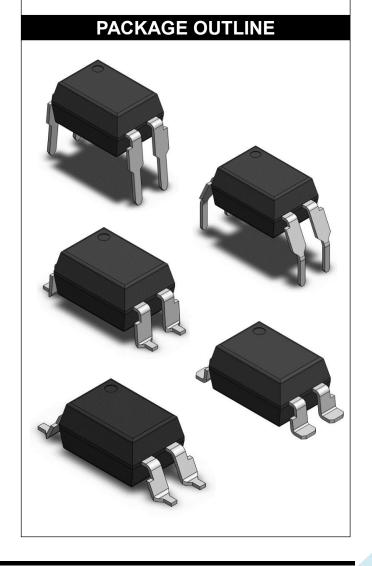
Applications

- AC line monitor
- Programmable controller
- Telephone line interface
- System appliance
- Measurement instrument

SCHEMATIC 4

PIN DEFINITION

- 1. Anode/Cathode
- 2. Cathode/Anode
 - 3. Emitter
 - 4. Collector





ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	VALUE	UNIT	NOTE			
INPUT							
Forward Current	I _F	±60	mA				
Peak Forward Current	I _{FP}	±1	Α	1			
Reverse Voltage	V _R	6	V				
Input Power Dissipation	Pı	100	mW				
OUTPUT							
Collector - Emitter Voltage	V _{CEO}	80	V				
Emitter - Collector Voltage	V _{ECO}	6	V				
Collector Current	Ic	50	mA				
Output Power Dissipation	Po	150	mW				
COMMON							
Total Power Dissipation	Ptot	200	mW				
Isolation Voltage	Viso	5000	Vrms	2			
Operating Temperature	Topr	-55~110	°C				
Storage Temperature	Tstg	-55~125	°C				
Soldering Temperature	Tsol	260	°C				

Note 1. 100µs pulse, 100Hz frequency

Note 2. AC For 1 Minute, R.H. = $40 \sim 60\%$



	ELECT	RICAL OI	PTICA	L CHA	RAC	TER	ISTICS at Ta=25°C		
PARAME	ETER	SYMBOL	MIN	TYP.	MAX.	UNIT	TEST CONDITION	NOTE	
INPUT									
Forward V	/oltage	V _F	-	1.24	1.4	V	$IF=\pm 10mA$		
Input Capa	citance	Cin	-	10	ı	pF	V=0, f=1kHz		
OUTPUT									
Collector Dar	k Current	I _{CEO}	-	-	100	nA	VCE=20V, IF=0		
Collector-I	Emitter	BV_CFO	80			- V	IC=0.1mA, IF=0		
Breakdown	Voltage	D V CEO	00	-	•	V			
Emitter-Co	ollector	BV_{ECO}	6			V	IE=0.1mA, IF=0		
Breakdown	Voltage	D A ECO		-	-	V			
	TRANSFER CHARACTERISTICS								
Current	TD814		20	-	400		IF=±1mA, VCE=5V		
Transfer	TD814A1	CTR	50	-	150	%			
Ratio	TD814B1		80	-	400				
CTF	R Symmetr	y	0.7	-	1.3		IF= \pm 1mA, VCE=5V		
Collector-I	Emitter	V.		0.06	0.06	0.2	2 V	IF = $\pm20mA$, IC = $1mA$	
Saturation	Voltage	$V_{CE(sat)}$	-	0.00	0.2	V	IF-±20IIIA, IC-IIIIA		
Isolation Re	sistance	R _{ISO}	10^12	10^14	-	Ω	DC500V, 40 ~ 60% R.H.		
Floating Cap	acitance	C _{IO}	-	0.4	1	pF	V=0, f=1MHz		
Response Ti	me (Rise)	tr	-	3	18	μs	VCE=2V, IC=2mA	3	
Response Ti	ime (Fall)	tf	-	4	18	μs	RL=100Ω	3	
Cut-off Fre	quency	fc	-	80	1	kHz	VCE=2V, IC=2mA RL=100Ω,-3dB	4	

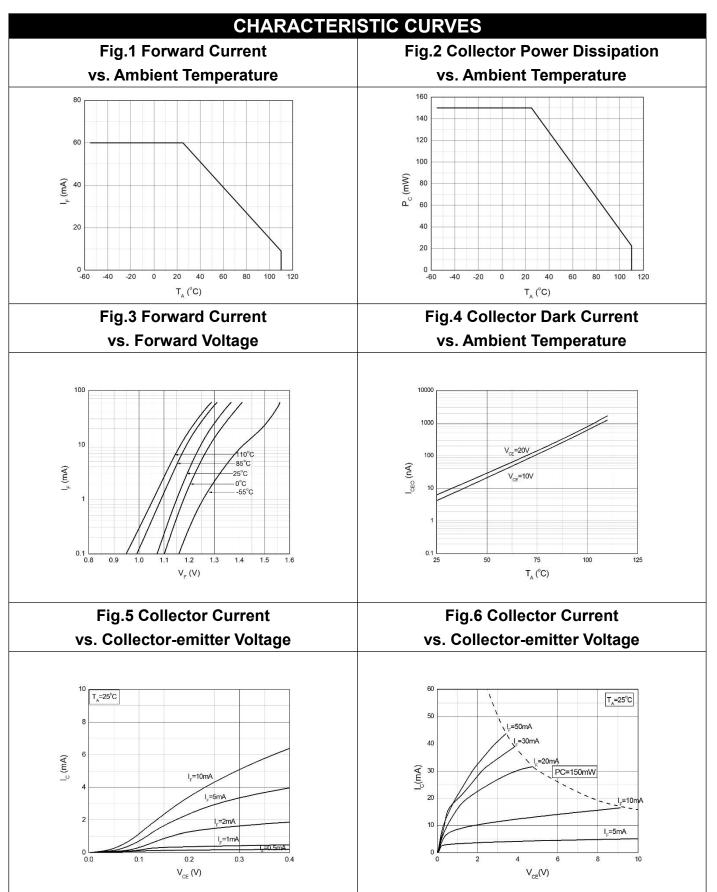
Note 3. Fig.12&13

Note 4. Fig.14



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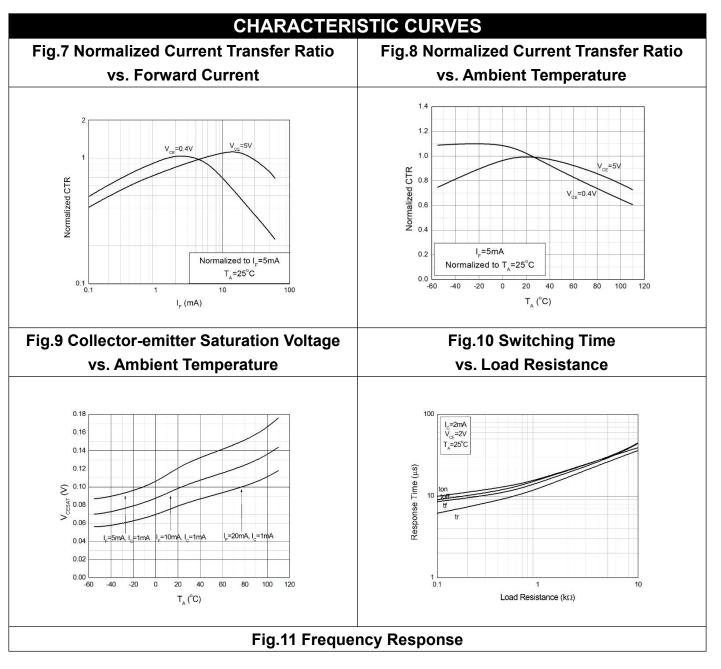
DIP4, AC Input, Photo Transistor Coupler



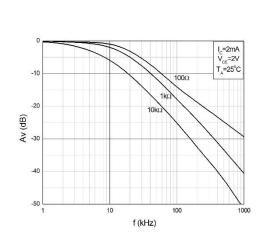
Rev: A02

Release Date: 2023/08/21









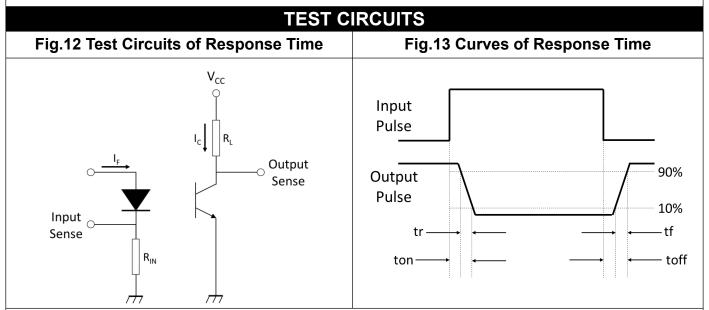
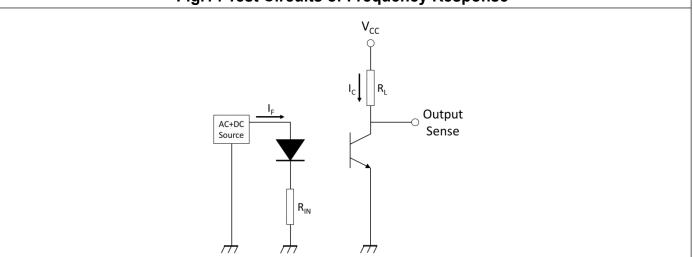


Fig.14 Test Circuits of Frequency Response





PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated) Standard DIP - Through Hole (DIP Type) 6.50±0.20 4.58±0.20 7.62±0.30 1.30±0.10 3.50±0.20 4.50±0.30 Тур.2.80 Typ.0.50 Typ.0.25 5°~15° Typ.2.54 7.62~9.50 Gullwing (400mil) Lead Forming – Through Hole (M Type) 6.50±0.20 4.58±0.20 7.62±0.30 1.30±0.10 3.50±0.20 4.58±0.30

Typ.0.50

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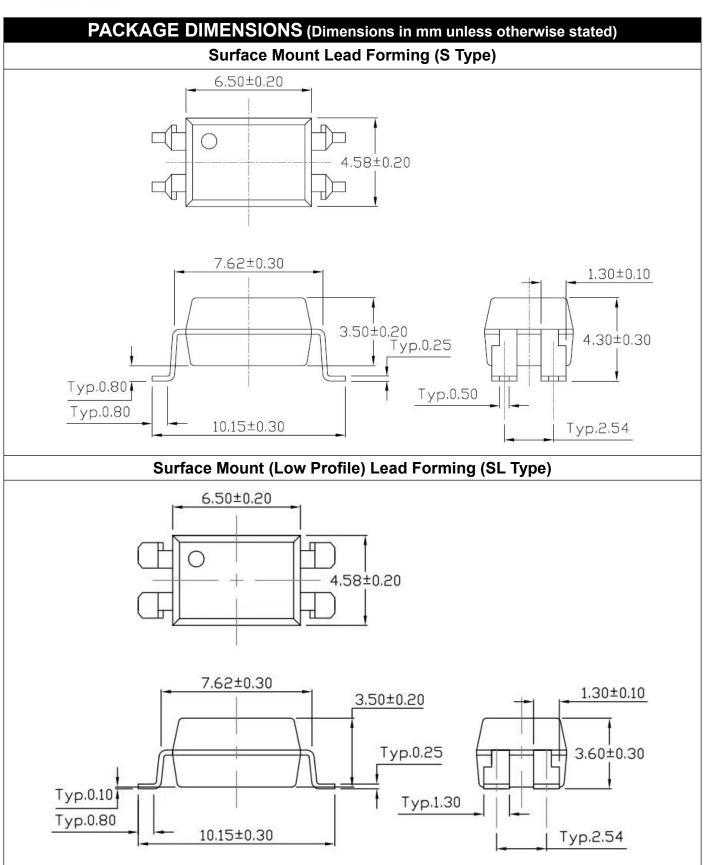
Typ.0.25

10.16±0.30

Typ.2.20

Typ.2.54

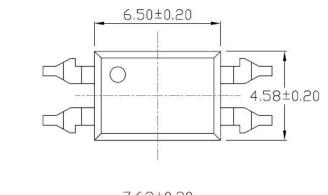


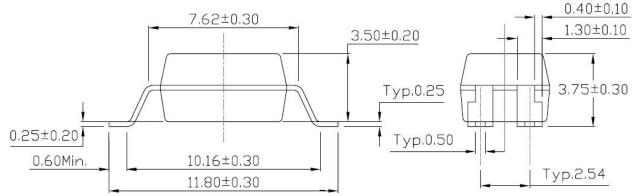




PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

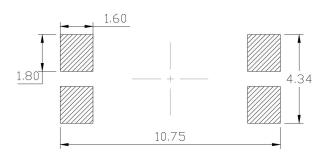
Surface Mount (Gullwing) Lead Forming (SLM Type)



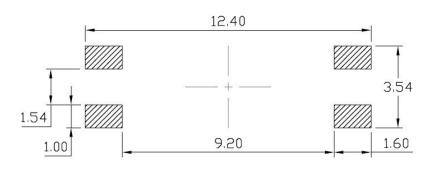


RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

Surface Mount Lead Forming & Surface Mount (Low Profile) Lead Forming



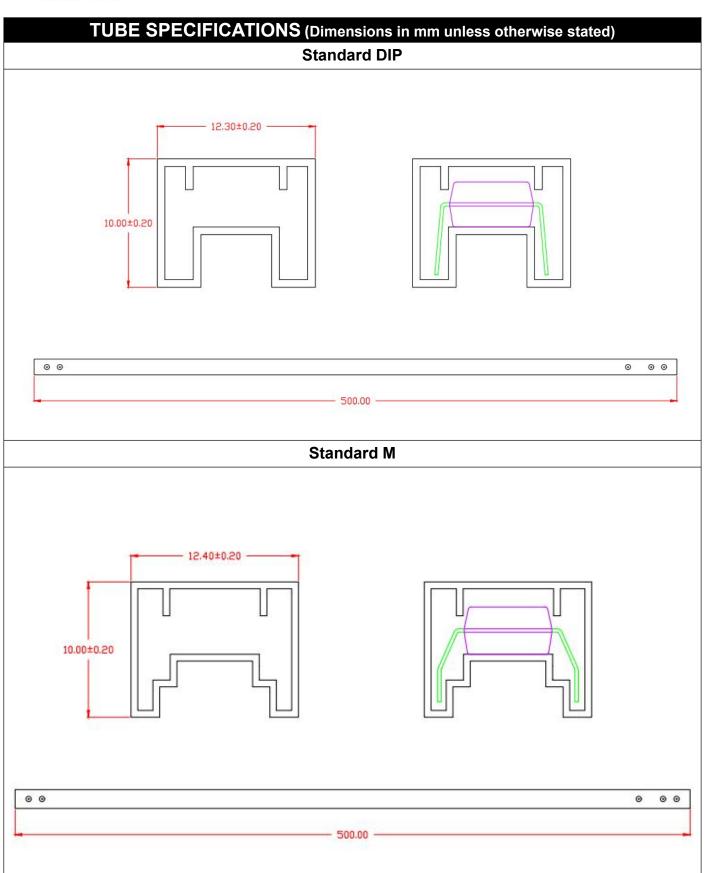
Surface Mount (Gullwing) Lead Forming



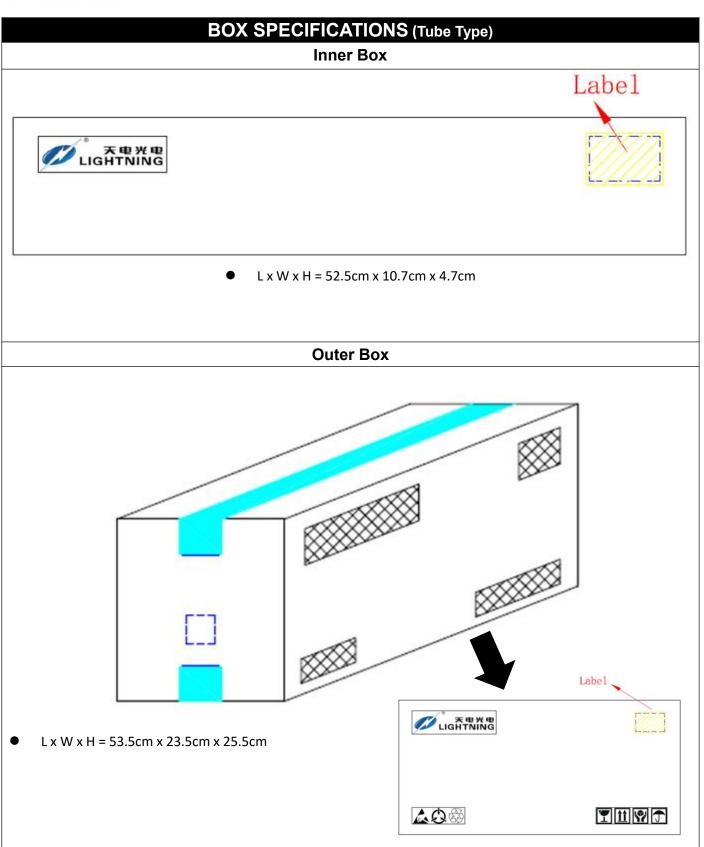


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DIP4, AC Input, Photo Transistor Coupler



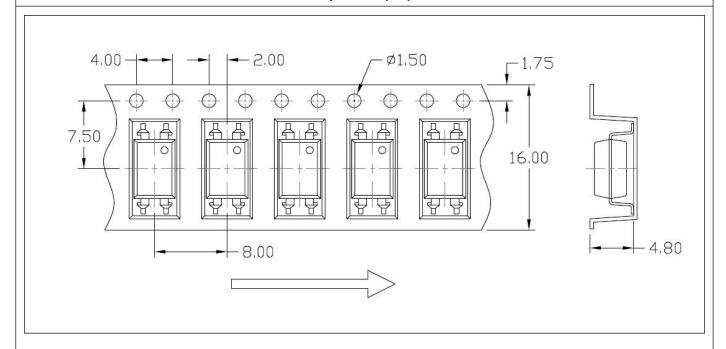




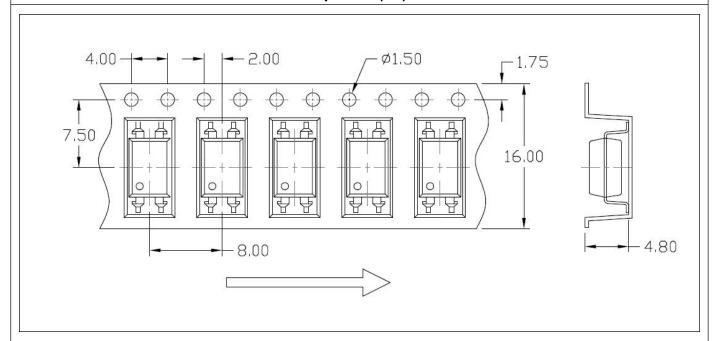


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

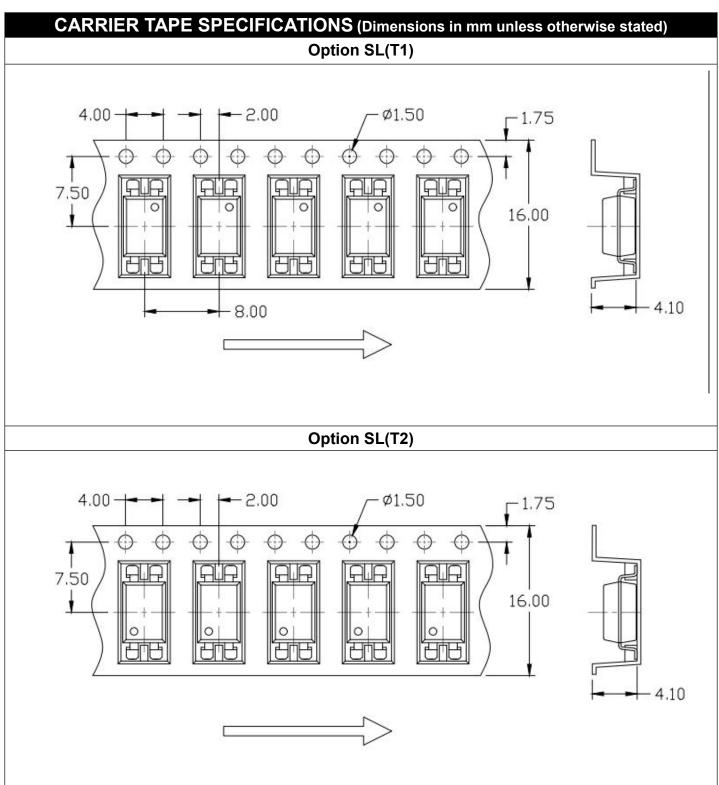
Option S(T1)



Option S(T2)



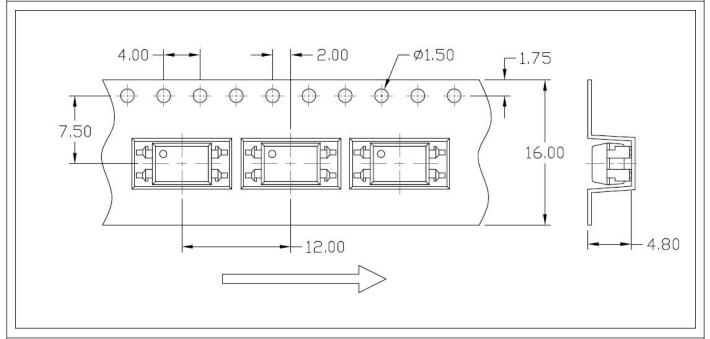




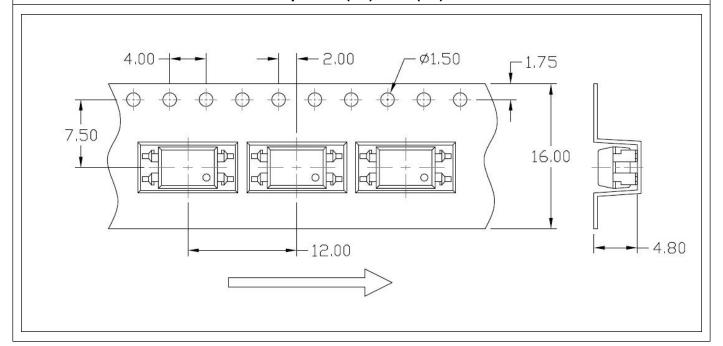


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option S(T3) & SL(T3)



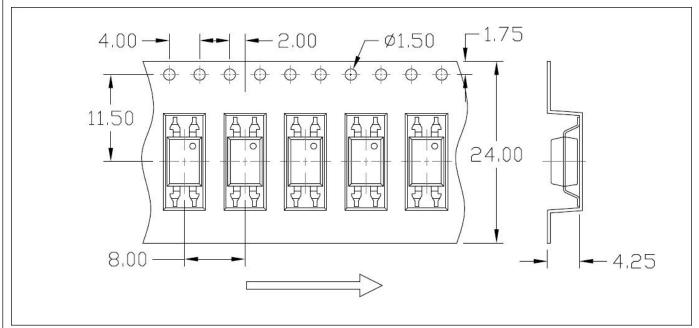
Option S(T4) & SL(T4)



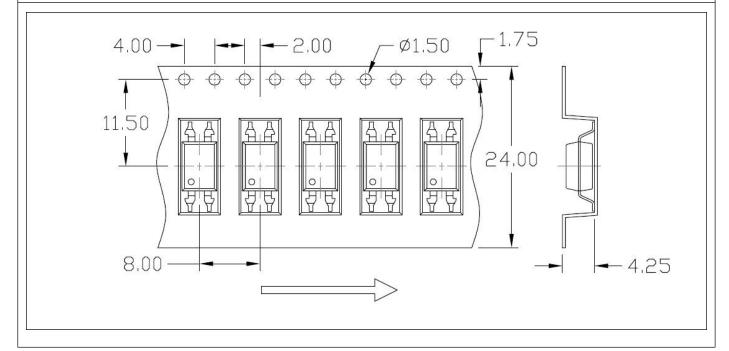


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

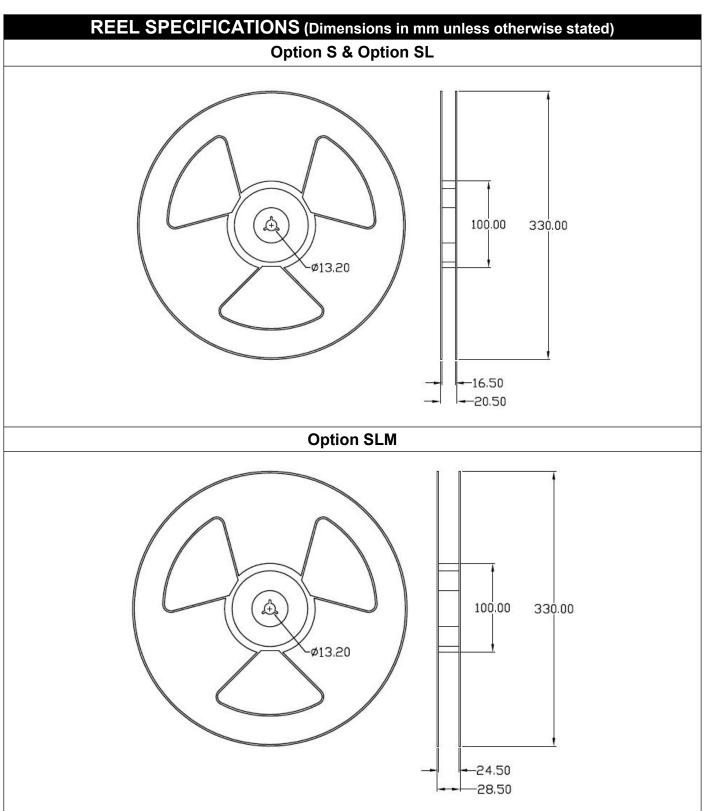




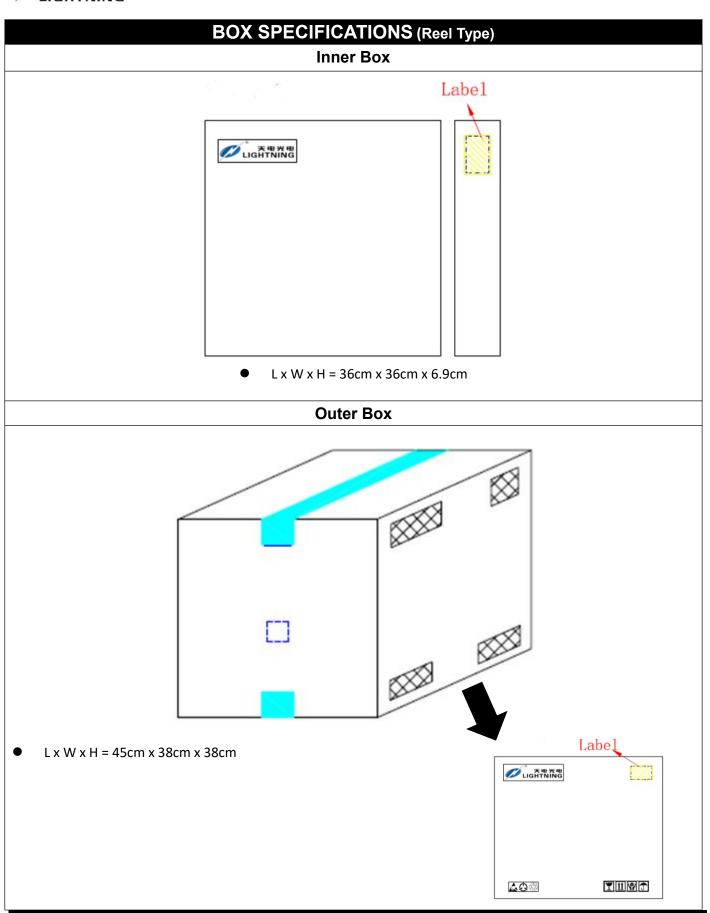
Option SLM(T2)













ORDERING AND MARKING INFORMATION

MARKING INFORMATION



TD : Company Abbr.

814 : Part Number

X : CTR Rank

V : VDE Option

Y : Fiscal Year

A : Manufacturing Code

WW : Work Week

ORDERING INFORMATION

TD814X1(Y)(Z)-GV

TD - Company Abbr.

814 - Part Number

X1 - Rank (A/B or None)

Y – Lead Form Option (M/S/SL/SLM/None)

1000 Units/Reel

Z – Tape and Reel Option (T1/T2/T3/T4)

G - Green

SLM(T2)

V – VDE Option (V or None)

LABEL INFORMATION



5 Inner box/Outer box = 15k Units

Packing Quantity Option Quantity Quantity - Inner box **Quantity – Outer box** None 100 Units/Tube 32 Tubes/Inner box 10 Inner box/Outer box = 32k Units Μ 100 Units/Tube 32 Tubes/Inner box 10 Inner box/Outer box = 32k Units 1500 Units/Reel 5 Inner box/Outer box = 22.5k Units S(T1) 3 Reels/Inner box 5 Inner box/Outer box = 22.5k Units S(T2) 1500 Units/Reel 3 Reels/Inner box 1000 Units/Reel S(T3) 3 Reels/Inner box 5 Inner box/Outer box = 15k Units S(T4) 1000 Units/Reel 3 Reels/Inner box 5 Inner box/Outer box = 15k Units SL(T1) 1500 Units/Reel 3 Reels/Inner box 5 Inner box/Outer box = 22.5k Units SL(T2) 1500 Units/Reel 3 Reels/Inner box 5 Inner box/Outer box = 22.5k Units 1000 Units/Reel 3 Reels/Inner box 5 Inner box/Outer box = 15k Units SL(T3) SL(T4) 1000 Units/Reel 3 Reels/Inner box 5 Inner box/Outer box = 15k Units 1000 Units/Reel 3 Reels/Inner box 5 Inner box/Outer box = 15k Units SLM(T1)

3 Reels/Inner box

IPC-020d-5-1



DIP4, AC Input, Photo Transistor Coupler

REFLOW INFORMATION REFLOW PROFILE Supplier T_p ≥ T_c User $T_p \le T_c$ T_C -5°C Supplier tp -T_c -5°C Temperature 📑 Max. Ramp Up Rate = 3°C/s Max. Ramp Down Rate = 6°C/s T_L T_{smax} Preheat Area T_{smin} 25 Time 25°C to Peak -Time ⇒

Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150°C
Temperature Max. (Tsmax)	150	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3°C/second max.	3°C/second max.
Liquidous Temperature (TL)	183°C	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (tP) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



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- This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or lifesaving applications or any other application which can result in human injury or death.
- Please contact LIGHTNING sales agent for special application request.
- Immerge unit's body in solder paste is not recommended.
- Parameters provided in datasheets may vary in different applications and performance may vary
 over time. All operating parameters, including typical parameters, must be validated in each
 customer application by the customer's technical experts. Product specifications do not expand or
 otherwise modify LIGHTNING's terms and conditions of purchase, including but not limited to the
 warranty expressed therein.
- Discoloration might be occurred on the package surface after soldering, reflow or long-time use. It neither impacts the performance nor reliability.